module arranged in the aperture, said cross-beam being secured to the electronic module to fix said electronic module to the plate.

37. The assembly according to claim **36**, wherein the thickness of said cross-beam is less than that of said plate.

38. The assembly according to claim **31**, wherein each electronic module is assembled to said frame by adhesive fasteners.

39. The assembly according to claim **38**, wherein said adhesive fasteners are formed by pieces of an adhesive strip or adhesive discs.

40. The assembly according to claim **39**, wherein said adhesive attachments are secured to said plate in notches provided at the periphery of each aperture.

41. The assembly according to claim **38**, wherein said adhesive attachments are formed by wires or thermoadhesive strips, which pass through the apertures provided in said plate and connect the electronic modules arranged in said apertures to said plate.

42. The assembly according to claim **31**, wherein each electronic module arranged in an aperture in said plate is connected to said plate via drops of resin or strips of resin, which define material bridges between the electronic module and said plate.

43. The assembly according to claim **31**, wherein a slot is provided between the electronic module and the corresponding aperture, which houses the electronic module, said slot being interrupted by the means for securing the electronic module to said plate.

44. The assembly according to claim **31**, wherein each electronic module has a substrate that carries electronic elements, the electronic module being assembled to said plate via said substrate.

45. An intermediate product produced during the card manufacture, wherein it is formed by an assembly according to claim **32**, said assembly including a plate with at least one, at least partially through aperture and at least one electronic module, which is housed at least partially in said at least one aperture, and by a filling resin, which fills at least most of the remaining space of said at least one aperture.

46. The intermediate product according to claim **45**, wherein it includes a covering resin that covers at least one of the top and bottom surfaces of said plate.

47. The intermediate product according to claim **46**, wherein said filling resin and said covering resin are formed by a same substance.

48. The intermediate product according to claim **46**, wherein at least one solid layer covers said resin, said solid layer forming a worksheet that does not adhere well to said resin and that will be removed during said card manufacture, such that said worksheet is not included in the finished cards.

49. A Method of manufacturing an intermediate product or at least one card including the following steps:

making an assembly according to claim **32**;

adding a filling resin and introducing this filling resin in a viscous liquid state in the remaining spaces of the apertures in the plate of said assembly, and

solidifying said filling resin.

50. The method according to claim **49**, wherein a covering resin is deposited over at least one of the top and bottom layers of said plate.

51. The method according to claim **50**, wherein said filling resin and said covering resin are formed by a same substance and are added simultaneously.

52. The method according to claim **50**, wherein at least one solid layer is added onto said covering resin to form a top layer and/or a bottom layer.

53. The method according to claim **52**, wherein said top layer, respectively said bottom layer, is a worksheet that does not adhere well to said covering resin, said worksheet being subsequently removed.

54. The method according to claim **52**, wherein said top layer, respectively said bottom layer, forms one layer of the manufactured cards, said solid layer adhering securely to said covering resin.

55. The method according to claim **49**, wherein said filling resin is spread out using at least one roller or a blade, which moves relative to said assembly, such that, after hardening, the filling resin fully fills said remaining spaces of said apertures.

56. The method according to claim **50**, wherein said filling resin and said covering resin are spread out using at least one roller or a blade, which moves relative to said assembly, such that, after hardening, the covering resin has an approximately flat external surface.

57. A method of manufacturing at least one card including the following steps:

making an intermediate product in accordance with claim **45**;

depositing a resin over at least one of the top and bottom surfaces of said intermediate product, and

applying pressure on said resin, which is deposited on said intermediate product and which is then in a non-solid state to form at least one card with a flat external surface, said resin compensating for variations in thickness in said intermediate product.

58. The method according to claim **57**, wherein the operations of depositing resin, applying pressure to said resin in a non-solid state and solidifying said resin are carried out at least twice in succession.

59. The method according to claim **57**, wherein said resin is added in a viscous liquid state.

60. The method according to claim **57**, wherein said deposited resin is covered by at least one worksheet that does not adhere well to said resin, said at least one worksheet being removed after the resin has solidified.

61. The method according to claim **57**, wherein there is a final step of adding at least one solid external layer onto said resin, said solid layer adhering securely to said resin.

62. The method according to claim **58**, wherein there is a final step of adding at least one solid external layer onto said resin, said solid layer adhering securely to said resin.

63. The method according to claim **58**, wherein said deposited resin is covered by at least one worksheet that does not adhere well to said resin, said at least one worksheet being removed after the resin has solidified.

64. The method according to claim **58**, wherein said resin is added in a viscous liquid state.

65. The method according to claim **51**, wherein said filling resin and said covering resin are spread out using at least one roller or a blade, which moves relative to said assembly, such that, after hardening, the covering resin has an approximately flat external surface.

66. The intermediate product according to claim **47**, wherein at least one solid layer covers said resin, said solid layer forming a worksheet that does not adhere well to said resin and that will be removed during said card manufacture, such that said worksheet is not included in the finished cards.